ICEP2011 Advanced Program (14, April)

14, April	Room A	Room B	Room C	Room D
	Keynote Speeches			
8:30	4 Advanced Packaging the New Decade E.J.Vardaman, TechSearch International / U.S.A.			
9:15	5 Ultrafast Semiconductor Thermal Imaging Kazuaki Yazawa, University of California Santa Cruz / U.S.A.			
10:00	**TA1:Korea Session-1**	**TB1:MFG-3**	**TC1:DMR-M**	**TD1:Advanced PKG-1**
10:10	TA1-1 Silicon Interposer Manufacturing Process and Its Application G.S.Kim, Kangnam University / Korea	TB1-1 A New Consortial development approach for Advanced Electronics Packaging B.Bader[1], B.Pfahl[1], H.Fu[2], [1]iNEMI, [2]iNEMI China / U.S.A., China	TC1-1 An R&D Informatics Solution towards the Structural and Electronic Properties of Cu Based Intermetallics A.Chatterjee, Accelrys / Japan	TD1-1 System Packaging by Embedding: Technologies, Examples and Perspectives T.Loeher[1], D.Schuetze[1], A.Ostmann[2], R.Aschenbrenner[2], [1]Technische Universitat Berlin, [2]Fraunhofer IZM / Germany
10:35	TA1-2 The advanced Wafer Level Package for high speed Memory S.T.Yang, J.I.Eom, D.W.Lee, M.S.Suh, Q.H.Chung, K.Y.Byun, Hynix / Korea	TB1-2 Proposal of package selection methodology for mobile product J.Asai, T.Hisada, K.Yonehara, IBM Japan / Japan	TC1-2 Leading Edge eMMC-BGA with Optimized Drop Reliability for Smart Phone Application W.J.Fan, E.Juang, W.Chang, S.Su, Powertech Technology / Taiwan, R.O.C.	TD1-2 Matching wire sweep design for 3-demensional and multi-chip module packaging during transfer molding H.S.Chen, J.C.Hsiung, H.K.Kung, Cheng Shiu University / Taiwan
11:00	TA1-3 Optimization of Interconnection Structure for Flip Chip Packaging with Ultra Low-K Dielectric S.Shim, W.Kim, S.Ryu, S.Yu.Shin, H.Lee, K.Chun, LG Innotek / Korea	TB1-3 Investigating the Effects of Area ratio and Aspect ratio Stencil Printing S.Mallik, M.Shafathullah, N.N.Ekere, University of Greenwich / UK	TC1-3 Package Design with Extremely Superior 2nd Reliability for SSD Application W.J.Fan, S.Su, E.Juang, W.Chang, Powertech Technology / Taiwan, R.O.C.	TD1-3 Next Generation fcCSP Packaging B.K.Appelt, H.Chung, C.Chen, M.Hung, ASE Group / U.S.A., Taiwan
11:25	**TA2:Korea Session-2**	**TB2:MFG-4**	**TC2:Thermal Management-3**	**TD2:Advanced PKG-2**
11:35	TA2-1 Life Estimation of Sn-3.0Ag-0.5Cu Pb-free Solder Joints for Passive Components of Automotive Electronics W.S.Hong, C.M.Oh, Korea Electronics Technology Institute / Korea	TB2-1 Component Solderability Testing with Board Level Soldering A.Sriyarunya[1], H.Tukiman[2], [1]Spansion(Thailand), [2]Spansion(Kuala Lumpur) / Thailand, Malaysia	TC2-1 Heat Transfer Performance of a Micro/Mini Cooling Device using Fins-installed Porous Media for the Next Generation Power Devices K.Yuki, Tokyo University of Science, Yamaguchi / Japan	TD2-1 Considerations for 2D Multi-die Fanout Wafer Level Packaging J.Hunt, Advanced Semiconductor Engineering / U.S.A.
12:00	TA2-2 The Enhanced Bondability of Sn-3.0Ag-0.5Cu Solder Joints with the Controlled Pd Contents in ENEPIG Surface Treatment Y.Kim, J.Yoon, S.-B.Jung, Sungkyunkwan University / Korea	TB2-2 Evaluating the effect of pad sizes on the inter-metallic layer formation and growth for Sn-Ag-Cu solders on Cu metallization P.Bernasko[1], S.Mallik[1], N.N.Ekere[1], R.Bhatti[1], G.Takyi[2], [1]University of Greenwich, [2]Kwame Nkrumah University Of Science & Technology / UK, Ghana	TC2-2 Liquid Cooling Network System for Energy Conservation in Date Centers M.Ouchi[1], Y.Abe[1], M.Fukagaya[2], H.Ohta[3], Y.Shinmoto[3], M.Sato[4], K.Iimura[4], [1]National Institute of Advanced Industrial Science and Technology, [2]SOHKi, [3]Kyushu University, [4]Utsunomiya University / Japan	TD2-2 Behavior of resin shrinkage in wafer-level packaging using pseudo-SOC technology A.Iida, Y.Onozuka, T.Nagano, H.Yamada, K.Itaya, Toshiba / Japan
12:25		TB2-3 Board level reliability Enhancement for a QFN Packaging A.Tseng, M.Lin, B.Hu, JW Chen, JM Wan, S.Lee, Y.S.Lai, ASE(US) / U.S.A.	TC2-3 Design of a Condensation Section for a Phase Change Cooling System A.Matsunaga, NEC / Japan	TD2-3 Ultra Low Temperature PBO-Polymer for Wafer Level Packaging Applications M.Toepper[1], N.Matsuie[2], T.Motobe[2], T.Minegishi[3], M.Knaus[4], T.Fischer[1], V.Bader[1], K.D.Lang[1], [1]Fraunhofer IZM, [2]HD MicroSystems Japan, [3]Hitachi Chemical, [4]HD MicroSystems Germany / Germany, Japan
12:50	Lunch Time			

ICEP2011 Advanced Program (14, April)

April 7

14, April	Room A	Room B	Room C	Room D
	TA3:3D/TSV-1 Taiwan Session	TB3:Thermal Management-4	TC3:Optoelectronics-1	TD3:MEMS-1, BEANS-1
13:35	TA3-1 Taiwan 3D IC Technology Perspectives S.L.Fu, I-Shou University / Taiwan	TB3-1 Cooling Performance of Compact Finned Heat Sinks under Combined Natural and Forced Convection Air Flows M.Ishizuka, T.Hatakeyama, T.Fukuya, S.Nakagawa, Toyama Prefectural University / Japan	TC3-1 Appication Specific LED Packaging for Automotive Forward-lighting Application F.Chen[1,2], K.Wang[1,2], M.Zhao[1,2], D.Wu[1,2], X.Luo[1,2], S.Liu[1,2], [1]Wuhan National Laboratory for Optoelectronics,[2]Huazhong University of Science & Technology / China	TD3-1 BEANS Project based on Multi-Disciplinary Fusion - Process Integration for Hetero-Functional Integrated Devices - (Session Invited) M.Takeda[1], A.Yusa[1], H.Fujita[1,2], [1]BEANS Project, [2]The University of Tokyo / Japan (50min)
14:00	TA3-2 Feasibility Study of a 3D IC Integration System-in-Packaging (SiP) from a 300mm Multi-Project Wafer (MPW) J.Lau, M.Dai, Y.Chao, W.Li, S.Wu, J.Hung, M.Hsieh, J.Chien, R.Tain, C.Tzeng, K.Lin, E.Hsin, C.Chen, M.Chen, C.Wu, J.Chen, J.Chien, C.Chiang, H.Chang, W.Tsai, C.Lee, T.Chang, C.Ko, T.Chen, S.Sheu, S.Wu, Y.Chen, R.Lo, T.Ku, M.Kao, D.Hu, Industrial Technology Resarch Institute / Taiwan, R.O.C.	TB3-2 Heart Transfer Correlation of Natural Convection in Square Enclosures with an Inner Object Y.Funawatashi, T.Kita, Toyama Prefectural University / Japan	TC3-2 Planar Interconnect for Solid State Lighting and Photonics R.A.Fillion, H.J.Neuhaus, C.E.Bauer, TechLead / U.S.A.	
14:25	TA3-3 Thermo-mechanical Stress Analysis of Though Silicon Via (TSV) by Finite Element Method D.S.Liu[1], C.Y.Tu[1], S.S.Yeh[1], H.Y.Chen[1], A.H.Liu[2], [1]National Chung Cheng University, [2]ChipMos Technologies / Taiwan R.O.C.	TB3-3 Improvement of the Thermal Management of Power LEDs by Functional 3D-Substrates with Embedded Fluidic T.Leneke, S.Hirsch, B.Schmidt Otto-von-Guericke-University Magdeburg / Germany	TC3-3 Study on high heat proof protection thin film for Ag reflective films for LED's H.Miyagawa, Osaka University / Japan	TD3-2 Silicon Microparticle Ejection Using Mist-jet Technology Y.Yokoyama[1], T.Murakami[1], T.Tokunaga[1], T.Itoh[1,2], [1]BEANS Project, [2]AIST / Japan
14:50	TA3-4 Reliability characterization of 20µm pitch microjoints assembled by a conventional reflow technique T.C.Chang, R.S.Cheng, P.C.Chang, Y.P.Hung, J.Y.Chang, T.F.Yang, S.Y.Huang, Industrial Technology Research Institute / Taiwan, R.O.C.	TB3-4 Hybrid Cooling Technology for Large Scale Computing Systems J.Wei, Fujitsu Advanced Technologies / Japan	TC3-4 A method to decap the LED devices effectively F.Jiao[1,2], R.Cheng[1,2], Q.Zhang[1,2], S.Liu[1,2], [1]Huazhong University of Science & Technology,[2]Wuhan National Laboratory for Optoelectronics / China	TD3-3 Continuous high speed thin film coating process on fiver-type substrates with die coater N.Shibayama[1], S.Takamatsu[1], T.Itoh[1,2], [1]BEANS Project, [2]AIST / Japan
15:15				
	TA4:3D/TSV-2	TB4:Thermal Management-5	TC4:Optoelectronics-2	TD4:MEMS-2, BEANS-2
15:25	TA4-1 Si Interposers with Thick Spiral Inductors for 3D Stacked Buck Converters K.Takemura[1,2], K.Ishida[3], Y.Ishii[1], K.Maeda[1], M.Takamiya[3], T.Sakurai[3], K.Baba[1,2], [1]NEC, [2]Association of Super-Advanced Electronic Technoligies, [3]The University of Tokyo / Japan	TB4-1 High Thermal Conductivity Multilayer Nanofilms for Reducing Thermal Hot Spots in LSI devaices F.Kato[1], K.Kikuchi[1], M.Aoyagi[1], T.Iwashita[2], H.Fujiwara[2], [1]National Institute of Advanced Industrial Science and Technology,[2]Furukawa Electric / Japan	TC4-1 Low-loss chip assembly for low-power optical I/O on waveguide - integrated organic carrier M.Tokunari, Y.Tsukada, K.Toriyama, H.Noma, S.Nakagawa, IBM Japan / Japan	TD4-1 Formation of Organic Crystalline Nanopillar Arrays and Their Application to Organic Photovoltaic M.Hirade[1,2], H.Nakanotani[1,2], M.Yahiro[1,2,3], C.Adachi[1,2,3], [1]BEANS Project, [2]Kyushu University, [3]Institute of Systems, Information Technologies and Nanotechnologies / Japan
15:50	TA4-2 Stacking of Known Good Rebuilt Wafers without TSV -Industrial Applications C.Val, P.Couderc, N.Boulay, 3D PLUS / France	TB4-2 Thermal Simulations and Measurements - a Combined Approach for Package Characterization A.Vass-Varnai, R.Bornoff, Y.Luo, A.Poppe, G.Farkas, M.Rencz, Mentor Graphics / Hungary	TC4-2 Surface activated bonding of optical chips using Au stud bumps for optical microsensor applications T.Sato, The University of Tokyo / Japan	TD4-2 Formation of organic semiconducting nano-dots by using vacuum deposition process and application for organic solar M.Nakata[1,2], K.Kawano[1,2], M.Yasumatsu[1,3], M.Yahiro[1,4], C.Adachi[1,3,4] [1]BEANS Project, [2]Panasonic Electric Works, [3]Kyushu University,[4]Institute of Systems, Information Technologies and Nanotechnologies / Japan
16:15	TA4-3 Development of 5µm Diameter Backside Cu TSV Technology for 3D LSI Y.Ohara, Y.Watanabe, K.Lee, T.Fukushima, M.Koyanagi, T.Tanaka, Tohoku University / Japan	TB4-3 Transient Heat Conduction Simulation of the Lidless Micro PGA Processor K.Nishi, AMD Japan / Japan	TC4-3 Spherulites Investigative of Poly (9,9-di-n-octy1-2,7-fluorene) (PFO) J.K.Ke, C.L.Chung, Y.J.Huang, S.L.Fu, I-Shou University / Taiwan, R.O.C.	TD4-3 Preparation of porous film at micro-scale and nano-scale by modified breath figure method Y.Zheng[1,3], Y.Kubowaki[2], K.Miyazaki[1,2], C.Adachi[1,3], [1]BEANS Project, [2]Kyushu Institute of Technology,[3]Kyushu University / Japan
16:40		TB4-4 On Effective Thermal Conductivity of Electronic Wiring Board Y.Koito, T.Tomimura, Kumamoto University / Japan	TC4-4 Photovoltaic Devices Using Electrospun Semi-conductive Polymer J.K.Ke, C.L.Chung, S.L.Fu, I-Shou University / Taiwan, R.O.C.	TD4-4 Minimizing Etching Damages of Organic Semiconductor Layers by Neutral Beams J.Adachi[1,2], T.Kubota[1,3], M.Yahiro[1,4], S.Sakukawa[1,5], C.Adachi[1,2], [1]BEANS Project, [2]Kyushu University,[3]The University of Tokyo, [4]Institute of Systems, Information Technologies and Nanotechnologies,[5]Tohoku University / Japan
17:05				
	TA5:Interconnection	TB5:MFG-5	TC5:Automotive	TD5:MEMS-3, BEANS-3
17:15	TA5-1 Effect of oxygen partial pressure on sintering nanoscale silver die-attachment on copper substrate H.Zheng[1], L.Xu[2], J.Calata[1], K.Ngo[1], S.Luo[3], G.-Q.Lu[1,2], [1]Virginia Tech, [2]Tianjin University, [3]NBE Technologies / U.S.A., China	TB5-1 Eco-fabircation of noble metal nanoparticle related materials by liquid-solid reaction Y.Hayashi, Tohoku University / Japan	TC5-1 Shrinkage and Sintering Behavior of a Low-Temperature Sinterable Nanosilver Die-Attach Paste T.Wang[1,2], M.Zhao[1], X.Chen[2], G.Q.Lu[1,2], K.Ngo[1], S.Luo[3], [1]Virginia Tech, [2]Tianjin University, [3]NBE Technologies / U.S.A., China	TD5-1 Site-Slective Binding of Nanoparticles onto a Silicon Chip by Peptides with an Affinity for Inorganic Materials Y.Shimada[1,2], M.Suzuki[1], M.Sugiyama[1,2], I.Kumagai[3], M.Umetsu[1,3], [1]BEANS Project, [2]The University of Tokyo,[3]Tohoku University / Japan
17:40	TA5-2 Natural Rubber-g-PVP/Silver Nanocmposites as Potential Conductive Adhesives N.H.H.Abu Bakar, J.Ismail, M.Abu Bakar, S.Yaakob, Universiti Sains Malaysia / Malaysia	TB5-2 Aerosol Jet Printing and Rapid Protoyping Methods for Flexible Structuring of 3D C.Goth, S.Putzo, J.Franke, University of Erlangen-Nuremberg / Germany	TC5-2 Low-Temperature Sintering of Nanoscale Silver Paste for Attaching Large-Area Silicon Devices K.Xiao, J.Calata, G.Q.Lu, Virginia Polytechnic Institute and State University / U.S.A.	TD5-2 Damage-free silicon etching using large diameter neutral beam source T.Kubota[1,2], S.Ueki[1], Y.Nishimori[1], G.Hashiguchi[1,3], M.Sugiyama[1,2], S.Samukawa[1,4], [1]BEANS Project, [2]The University of Tokyo,[3]Shizuoka University, [4]Tohoku University / Japan
18:05	TA5-3 Bondability of Low Temperature Sinter Bonding Using Ag2O Pastes with Polyethylene Glycols T.Yagishita, T.Ogura, A.Hirose, Osaka University / Japan	TB5-3 Fabrication and application of Ag nanoparticles by ultrasonic process D.Ishikawa[1], T.Abe[1], K.Toisawa[2], Y.Hayashi[2], H.Takizawa[2], [1]Hitachi Cable, [2]Tohoku University / Japan	TC5-3 Thermal expansion behavior of Cu6Sn5 in high temperature lead-free solder joints D.Mu, J.Read, Y.F.Yang, K.Nogita, The University of Queensland / Australia	TD5-3 Embedded Nano-channel Fabricated in Fused Silica by Femtosecond Laser Irradiation and Wet Etching for Nano-scale Fluid Devices O.Nukaga[1], S.Yamamoto[2], K.V.Tabata[1,3], T.Kubota[1,4], S.Samukawa[1,5], M.Sugiyama[1,4], [1]BEANS Project, [2]Fujikura, [3]Osaka University, [4]The University of Tokyo,[5]Tohoku University / Japan
18:30				